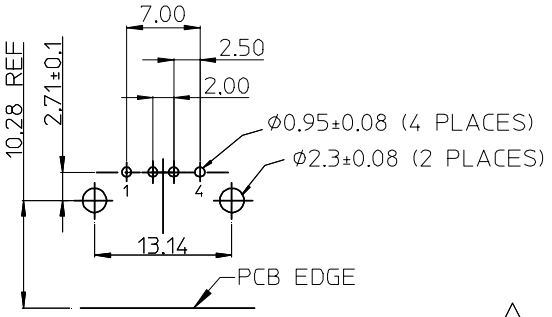
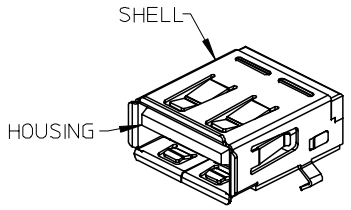
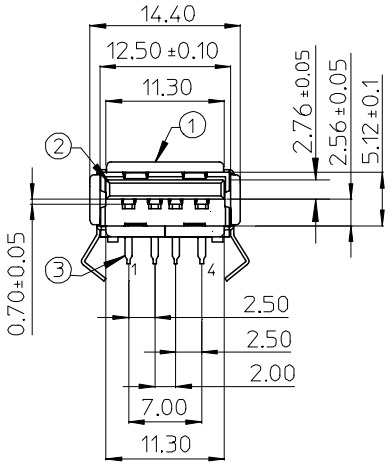
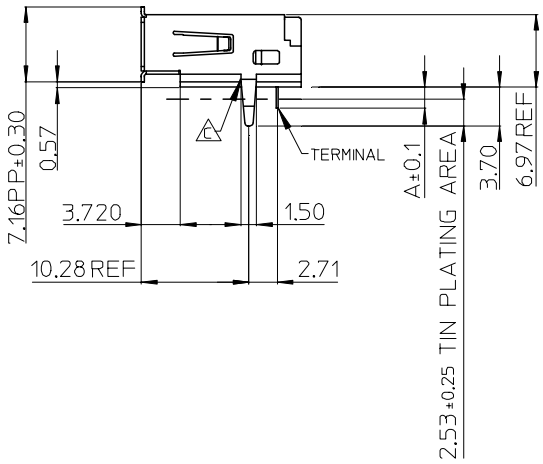




PCB LAYOUT (BOTTOM VIEW)







NOTES:
1.MATERIAL:
① METAL SHELL:COPPER ALLOY.
② HOUSING: SEE CHART, GLASS FIBER FILLED,UL94-V0.
③ TERMINAL:COPPER ALLOY.
2.TERMINAL:
CONTACT AREA:(a)GOLD FLASH.
(b) GOLD (Au).
THICKNESS=30 MICROINCH MINIMUM.
SOLDER TAIL:TIN-LEAD (Sn-Pb), ALLY
THICKNESS=75 MICROINCH MINIMUM.
UNDER PLATED:NICKEL (Ni).
THICKNESS=50 MICROINCH MINIMUM.
METAL SHELL:SEE CHART.
3.RECOMMENDED PCB THICKNESS:1.60 ± 0.05 OR 1.20 ± 0.05
4.PRODUCT SPECIFICATION:REFER TO PS-67998-0000
5.TEST SUMMARY:REFER TO TS-67643-001
6.PACKAGE : REFER TO PK-67643-001

REV	DESCRIPTION	
C	MODIFIED METAL SHELL EC NO: SHA2005529296 DRWN:JCHEN12 2005/05/23 CH'KD: 2005/05/24 APPR:WWSCHANG 2005/05/25	

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± 0.25	± ---

ANGULAR ± 3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	1:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	IVY-LIN 2005/05/05
CHECKED BY / DATE	ALLIN 2005/05/05
APPROVED BY / DATE	WWSCHANG 2005/05/05
MATERIAL NO.	SEE TABLE
TITLE	USB A TYPE RCPT SGL RA THROUGH HOLE WITHOUT FLANGE
	MOLEX INCORPORATED
DOCUMENT NO.	SD-67643-001
SHEET NO.	1 OF 2
SIZE	A4

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0010	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS TIN-LEAD PLATED AREA. TIN-LEAD (Sn-Pb) AT SOLDER AREA. UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE) SURFACE APPEARANCE:BRIGHT.	NON IR REFLOW PROCESS
67643-1010	POLYESTER	WHITE			
67643-2010	HIGH TEMPERATURE NYLON	BLACK			FOR IR REFLOW PROCESS
67643-3010	HIGH TEMPERATURE NYLON	WHITE			
67643-0011	POLYESTER	BLACK	GOLD PLATING 30 MICROINCH	NON IR REFLOW PROCESS: SOLDER TAIL:TIN-LEAD (Sn-Pb) UNDER PLATE:NICKEL (Ni). SURFACE APPEARANCE:BRIGHT.	NON IR REFLOW PROCESS
67643-1011	POLYESTER	WHITE			
67643-2011	HIGH TEMPERATURE NYLON	BLACK			FOR IR REFLOW PROCESS
67643-3011	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.60±0.05			
DIMENSION "A"		2.60			

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0030	HIGH TEMPERATURE NYLON	BLACK	GOLD FLASH	IR REFLOW PROCESS TIN-LEAD PLATED AREA TIN-LEAD (Sn-Pb) AT SOLDER AREA UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE) SURFACE APPEARANCE:BRIGHT.	FOR IR REFLOW PROCESS
67643-1030	HIGH TEMPERATURE NYLON	WHITE			
67643-0031	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 30 MICROINCH		
67643-1031	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.20±0.05			
DIMENSION "A"		2.00			

SEE SHEET 1
EC NO: SHA2005[illegible]2796 2005/05/23
DRWN: JCHEN12 2005/05/24
CH'KD: 2005/05/25
APPR: WWSCHANG
DESCRIPTION
C
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 1:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	IVY-LIN	2005/05/05
CHECKED BY	ALLIN	2005/05/05
APPROVED BY	WWSCHANG	2005/05/05

TITLE: USB A TYPE RCPT SGL RA THROUGH HOLE WITHOUT FLANGE

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-67643-001
SHEET NO.: 2 OF 2

SIZE A4

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION